

**AMENDMENTS TO THE SPECIFICATION:**

Page 1, line 4 thereof, after the title, please add the following new paragraph:

**CROSS-REFERENCE TO RELATED APPLICATIONS**

This application is a division of co-pending U.S. Application No. 10/019,508, filed on December 21, 2001, and entitled, "Side-Emission Type Semiconductor Light-Emitting Device and Manufacturing Method Thereof", the disclosure of which is incorporated herein by reference.

**AMENDMENT TO THE CLAIMS:**

1. (Cancelled)
2. (Cancelled)
3. (Cancelled)
4. (Original) A side-emission type semiconductor light-emitting device, comprising:
  - a substrate formed with an electrode;
  - an LED chip bonded onto said substrate;
  - a transparent or translucent resin with which said LED chip is molded; and
  - a reflector which reflects a light emitted from said LED chip, wherein said transparent or translucent resin has a convex portion, and said reflector has a concave portion to be fitted into said convex portion.
5. (Original) A side-emission type semiconductor light-emitting device according to claim 4, wherein said concave portion is a throughhole having a diameter which becomes larger from one main surface to other main surface of said reflector.